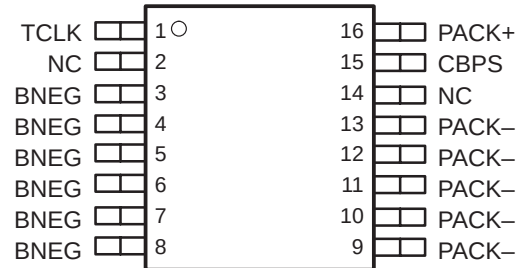


UCC3952-1, UCC3952-2, UCC3952-3, UCC3952-4 Single-Cell Lithium-Ion Battery Protection IC

SLUS400D – AUGUST 2000

- Protects Sensitive Lithium-Ion Cells From Overcharging and Over-Discharging
- Dedicated for One-Cell Applications
- Integrated Low-Impedance MOSFET Switch and Sense Resistor
- Precision Trimmed Overcharge and Overdischarge Voltage Limits
- Extremely Low Power Drain
- 3-A Current Capacity
- Overcurrent and Short-Circuit Protection
- Reverse Charger Protection
- Thermal Protection

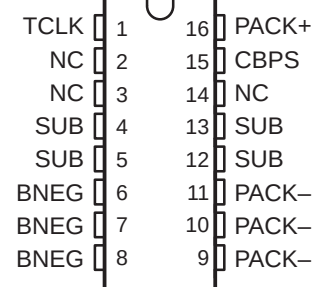
PW PACKAGE
(TOP VIEW)



description

The UCC3952 monolithic BiCMOS lithium-ion battery protection circuit increases the useful operating life of a one-cell rechargeable battery pack. Cell protection features include internally trimmed charge and discharge voltage limits, discharge current limit with a delayed shutdown, and an ultra-low-current sleep mode state when the cell is discharged. Additional features include an on-chip MOSFET for reduced external component count and a charge pump for reduced power losses while charging or discharging a low-cell-voltage battery pack. This protection circuit requires one external capacitor and can operate and safely shut down in a short circuit condition.

DP PACKAGE
(TOP VIEW)



Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.

PRODUCTION DATA information is current as of publication date. Products conform to specifications per the terms of Texas Instruments standard warranty. Production processing does not necessarily include testing of all parameters.



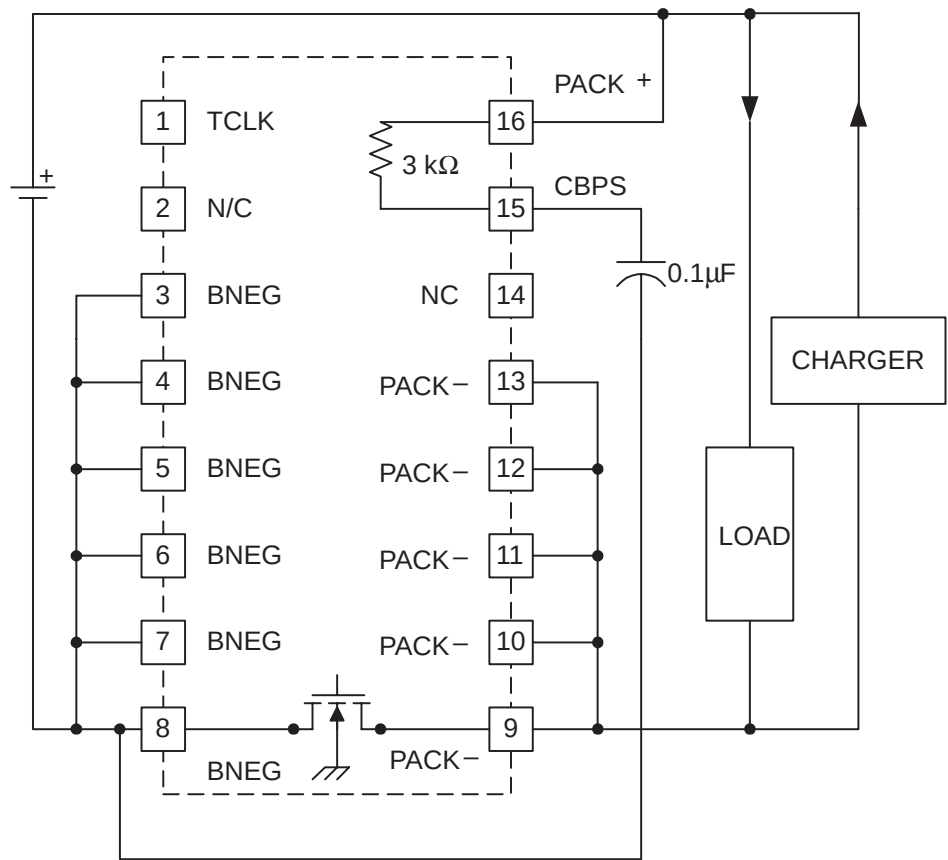
POST OFFICE BOX 655303 • DALLAS, TEXAS 75265

Copyright © 2000, Texas Instruments Incorporated

UCC3952-1, UCC3952-2, UCC3952-3, UCC3952-4
Single-Cell Lithium-Ion Battery Protection IC

SLUS400D – AUGUST 2000

application diagram



AVAILABLE OPTIONS

T _A	PACKAGES	
	TSSOP-16 (PW)	SOIC-16 (DP)
-20°C to 70 °C	UCC3952PW-1	UCC3952DP-1
	UCC3952PW-2	UCC3952DP-2
	UCC3952PW-3	UCC3952DP-3
	UCC3952PW-4	UCC3952DP-4

UCC3952-1, UCC3952-2, UCC3952-3, UCC3952-4 Single-Cell Lithium-Ion Battery Protection IC

SLUS400D – AUGUST 2000

absolute maximum ratings over operating free-air temperature (unless otherwise noted)[†]

Supply voltage (PACK+ to BNEG)	7 V
Maximum forward voltage (PACK+ to PACK-)	16 V
Maximum reverse voltage (where PACK+ to BNEG = 5V)	-8 V
Maximum cell continuous charge current	3 A
Junction temperature, T _J	-55°C to 150°C
Storage Temperature range, T _{stg}	-65°C to 150°C

[†] Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTE 1: Currents are positive into, negative out of the specified terminal. Consult Packaging Section of Data Book for thermal limitations and considerations of packages. All voltages are referenced to GND.

electrical characteristics, T_A = -20°C to 70°C, all voltages are with respect to BNEG (unless otherwise stated)

state transition threshold

PARAMETER		TEST CONDITIONS	MIN	TYP	MAX	UNITS
V _(OV)	Normal to overcharge voltage	UCC3952-1	4.15	4.20	4.25	V
		UCC3952-2	4.20	4.25	4.30	
		UCC3952-3	4.25	4.30	4.35	
		UCC3952-4	4.30	4.35	4.40	
V _(OVR)	Overcharge to normal recovery voltage	UCC3952-1	3.85	3.90	3.95	V
		UCC3952-2	3.90	3.95	4.00	
		UCC3952-3	3.95	4.00	4.05	
		UCC3952-4	4.00	4.05	4.10	
V _(UV)	Normal to undercharge		2.25	2.35	2.45	V
V _(UVR)	Undercharge to normal recovery		2.55	2.65	2.75	V
t _{d(OD)}	Overcharge delay time		10	25	40	ms

short circuit protection

PARAMETER		TEST CONDITIONS	MIN	TYP	MAX	UNITS
I _(THLD)	Discharge current limit	PACK+ = 3.7 V	3.0		6.0	A
t _{d(DLY)}	Discharge current delay	PACK+ = 3.7 V, I _L = 6 A	1		3.0	ms
R _(RESET)	Discharge current reset resistance	PACK+ = 3.7 V	7.5			MΩ

bias

PARAMETER		TEST CONDITIONS	MIN	TYP	MAX	UNITS
I _{DD}	Supply current	V _(UV) < V _(PACK) < V _(OV)		5	8	μA
I _{DD(OV)}	Operating supply current in overvoltage	V _(OV) < V _(PACK)		11	24	μA
I _(SD)	Shutdown current	V _(PACK) = 2.0 V			2.5	μA
V _(min)	Minimum cell voltage when all circuits are fully functional				1.7	V
t _{d(OV)}	Overvoltage delay time		1		2	s



UCC3952-1, UCC3952-2, UCC3952-3, UCC3952-4

Single-Cell Lithium-Ion Battery Protection IC

SLUS400D – AUGUST 2000

electrical characteristics, $T_A = -20^{\circ}\text{C}$ to 70°C , all voltages are with respect to BNEG (unless otherwise stated) (continued)

FET switch

PARAMETER		TEST CONDITIONS	MIN	TYP	MAX	UNITS
$V_{(\text{PACK}-)}$	Voltage at PACK-	$\text{PACK+} > V_{\text{OV}}$, $I_{(\text{SWITCH})} = 1 \text{ mA to } 2 \text{ A}$, Battery overcharged state switch permits discharge current only.		100	400	mV
		$\text{PACK+} = 2.5 \text{ V}$, $I_{(\text{SWITCH})} = -1 \text{ mA to } -2 \text{ A}$, Battery overdischarged state switch permits charge current only.	-600	-100		mV
R_{ON}	Series resistance of the device	$\text{PACK+} = 2.5 \text{ V}$, In normal mode (when not in OV or UV). This value includes package and bondwire resistance.		50	75	m Ω

thermal shutdown

PARAMETER		TEST CONDITIONS	MIN	TYP	MAX	UNITS
$T_{(\text{SD})}$	Thermal shutdown temperature (see Note 2)			135		$^{\circ}\text{C}$

NOTE 2: This parameter is ensured by design and is not production tested.

detailed description

pin descriptions

BNEG

Connect the negative terminal of the battery to this pin.

PACK+

Connect to the positive terminal of the battery. This pin is available to the user.

CBPS

This power supply bypass pin is connected to PACK+ through an internal 3-k Ω resistor. An external 0.1- μF capacitor must be connected between this pin and BNEG.

PACK-

The negative terminal of the battery pack (negative terminal available to the user). The internal FET switch connects this terminal to the BNEG terminal to give the battery pack user appropriate access to the battery. In an overcharged state, only discharge current is permitted. In an overdischarged state, only charge current is permitted.

SUB (DP Package Only)

Do not connect. These pins must be electrically isolated from all other pins. The SUB pins may be soldered to an isolated copper pad for heatsinking. However, most applications do not require heatsinking.

TCLK

Production test mode pin. This pin is used to provide a high-frequency clock to the IC during production testing. In an application, this pin is left unconnected or tied to BNEG.



APPLICATION INFORMATION

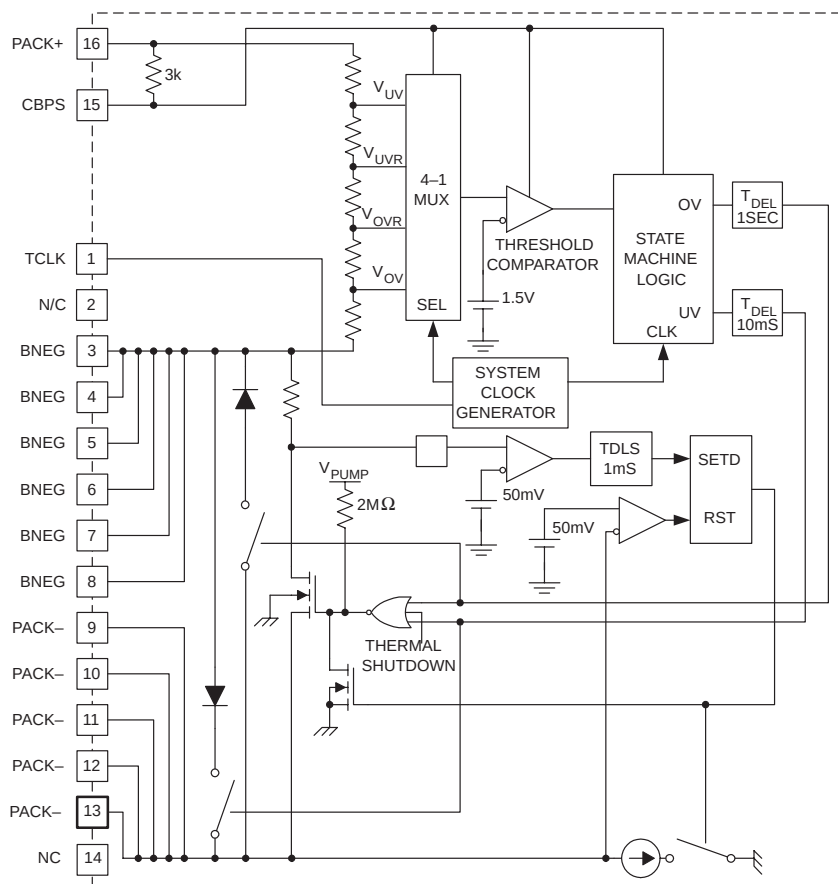


Figure 1. Detailed Block Diagram

battery voltage monitoring

The battery cell voltage is sampled every 8 ms by connecting a resistor divider across it and comparing the resulting voltage to a precision internal reference voltage. Under normal conditions (cell voltage is below overvoltage threshold and above undervoltage threshold), the UCC3952 consumes less than 10 μ A of current and the internal MOSFET is fully turned on with the aid of a charge pump.

When the cell voltage falls below the undervoltage threshold for two consecutive samples, the IC disconnects the load from the battery pack and enters a super-low-power mode. The pack remains in this state until it detects the application of a charger, at which point charging is enabled. The requirement of two consecutive readings below the undervoltage threshold filters out momentary drops in cell voltage due to load transients, preventing nuisance trips.

If the cell voltage exceeds the overvoltage threshold for 1 second, charging is disabled; however, discharge current is still allowed. This feature of the IC is explained further in the *controlled charge/discharge mode* section of this document.

UCC3952-1, UCC3952-2, UCC3952-3, UCC3952-4

Single-Cell Lithium-Ion Battery Protection IC

SLUS400D – AUGUST 2000

APPLICATION INFORMATION

overcurrent monitoring and protection

Discharge current is continuously monitored via an internal sense resistor. In the event of excessive current, an overcurrent condition is declared if the high current (over 3 A) persists for over 1 ms. This delay allows for charging of the system bypass capacitors without tripping the overcurrent protection. A 0.1- μ F capacitor on the CBPS pin provides momentary holdup for the IC to assure proper operation in the event that a hard short suddenly pulls the cell voltage below the minimum operating voltage.

Once an overcurrent condition has been declared, the internal MOSFET turns off. To return the device to normal operation, the UCC3952 requires a load impedance greater than 7.5 M Ω across PACK+ to PACK-. This impedance is typically achieved by removing the battery pack from the system. At this point, the pack returns to its normal state of operation.

controlled charge/discharge mode

When the chip senses an overvoltage condition, it prevents any additional charging, but allows discharge. This is accomplished by activating a linear control loop, which controls the gate of the MOSFET based on the differential voltage across its drain-to-source terminals. The linear loop attempts to regulate the differential voltage across the MOSFET to 100 mV. When a light load is applied to the part, the loop adjusts the impedance of the MOSFET to maintain 100 mV across it. As the load increases, the impedance of the MOSFET is decreased to maintain the 100-mV control. At heavy loads (still below the overcurrent limit), the loop does not maintain regulation and drives the gate of the MOSFET to the battery voltage (not the charge-pump output voltage). The MOSFET $R_{DS(on)}$ in the overvoltage state is higher than $R_{DS(on)}$ during normal operation. The voltage drop (and associated power loss) across the internal MOSFET in this mode of operation is still significantly lower than the typical solution of two external back-to-back MOSFETs, where the body diode is conducting.

When the chip senses an undervoltage condition, it disconnects the load from the battery pack and shuts itself down to minimize current drain from the battery. Several circuits remain powered and detect placement of the battery pack into a charger. Once the charger presence is detected, the linear loop is activated and the chip allows charging current into the battery. This linear control mode of operation is in effect until the battery voltage reaches a level of V_{UVR} , at which time normal operation is resumed.



PACKAGING INFORMATION

Orderable Device	Status ⁽¹⁾	Package Type	Package Drawing	Pins	Package Qty	Eco Plan ⁽²⁾	Lead/Ball Finish	MSL Peak Temp ⁽³⁾
UCC3952DP-1	ACTIVE	SOIC	D	16	40	None	CU SNPB	Level-1-220C-UNLIM
UCC3952DP-2	ACTIVE	SOIC	D	16	40	None	CU SNPB	Level-1-220C-UNLIM
UCC3952DP-3	ACTIVE	SOIC	D	16	40	None	CU SNPB	Level-1-220C-UNLIM
UCC3952DP-4	ACTIVE	SOIC	D	16	40	None	CU SNPB	Level-1-220C-UNLIM
UCC3952PW-1	ACTIVE	TSSOP	PW	16	90	None	CU NIPDAU	Level-2-220C-1 YEAR
UCC3952PW-2	ACTIVE	TSSOP	PW	16	90	None	CU NIPDAU	Level-2-220C-1 YEAR
UCC3952PW-3	ACTIVE	TSSOP	PW	16	90	None	CU NIPDAU	Level-2-220C-1 YEAR
UCC3952PW-4	ACTIVE	TSSOP	PW	16	90	None	CU NIPDAU	Level-2-220C-1 YEAR
UCC3952PWTR-1	ACTIVE	TSSOP	PW	16	2000	None	CU NIPDAU	Level-2-220C-1 YEAR
UCC3952PWTR-2	ACTIVE	TSSOP	PW	16	2000	None	CU NIPDAU	Level-2-220C-1 YEAR
UCC3952PWTR-3	ACTIVE	TSSOP	PW	16	2000	None	CU NIPDAU	Level-2-220C-1 YEAR
UCC3952PWTR-4	ACTIVE	TSSOP	PW	16	2000	None	CU NIPDAU	Level-2-220C-1 YEAR

⁽¹⁾ The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBsolete: TI has discontinued the production of the device.

⁽²⁾ Eco Plan - May not be currently available - please check <http://www.ti.com/productcontent> for the latest availability information and additional product content details.

None: Not yet available Lead (Pb-Free).

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Green (RoHS & no Sb/Br): TI defines "Green" to mean "Pb-Free" and in addition, uses package materials that do not contain halogens, including bromine (Br) or antimony (Sb) above 0.1% of total product weight.

⁽³⁾ MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

Important Information and Disclaimer: The information provided on this page represents TI's knowledge and belief as of the date that it is provided. TI bases its knowledge and belief on information provided by third parties, and makes no representation or warranty as to the accuracy of such information. Efforts are underway to better integrate information from third parties. TI has taken and continues to take reasonable steps to provide representative and accurate information but may not have conducted destructive testing or chemical analysis on incoming materials and chemicals. TI and TI suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.

In no event shall TI's liability arising out of such information exceed the total purchase price of the TI part(s) at issue in this document sold by TI to Customer on an annual basis.

IMPORTANT NOTICE

Texas Instruments Incorporated and its subsidiaries (TI) reserve the right to make corrections, modifications, enhancements, improvements, and other changes to its products and services at any time and to discontinue any product or service without notice. Customers should obtain the latest relevant information before placing orders and should verify that such information is current and complete. All products are sold subject to TI's terms and conditions of sale supplied at the time of order acknowledgment.

TI warrants performance of its hardware products to the specifications applicable at the time of sale in accordance with TI's standard warranty. Testing and other quality control techniques are used to the extent TI deems necessary to support this warranty. Except where mandated by government requirements, testing of all parameters of each product is not necessarily performed.

TI assumes no liability for applications assistance or customer product design. Customers are responsible for their products and applications using TI components. To minimize the risks associated with customer products and applications, customers should provide adequate design and operating safeguards.

TI does not warrant or represent that any license, either express or implied, is granted under any TI patent right, copyright, mask work right, or other TI intellectual property right relating to any combination, machine, or process in which TI products or services are used. Information published by TI regarding third-party products or services does not constitute a license from TI to use such products or services or a warranty or endorsement thereof. Use of such information may require a license from a third party under the patents or other intellectual property of the third party, or a license from TI under the patents or other intellectual property of TI.

Reproduction of information in TI data books or data sheets is permissible only if reproduction is without alteration and is accompanied by all associated warranties, conditions, limitations, and notices. Reproduction of this information with alteration is an unfair and deceptive business practice. TI is not responsible or liable for such altered documentation.

Resale of TI products or services with statements different from or beyond the parameters stated by TI for that product or service voids all express and any implied warranties for the associated TI product or service and is an unfair and deceptive business practice. TI is not responsible or liable for any such statements.

Following are URLs where you can obtain information on other Texas Instruments products and application solutions:

Products		Applications	
Amplifiers	amplifier.ti.com	Audio	www.ti.com/audio
Data Converters	dataconverter.ti.com	Automotive	www.ti.com/automotive
DSP	dsp.ti.com	Broadband	www.ti.com/broadband
Interface	interface.ti.com	Digital Control	www.ti.com/digitalcontrol
Logic	logic.ti.com	Military	www.ti.com/military
Power Mgmt	power.ti.com	Optical Networking	www.ti.com/opticalnetwork
Microcontrollers	microcontroller.ti.com	Security	www.ti.com/security
		Telephony	www.ti.com/telephony
		Video & Imaging	www.ti.com/video
		Wireless	www.ti.com/wireless

Mailing Address: Texas Instruments
Post Office Box 655303 Dallas, Texas 75265

Copyright © 2005, Texas Instruments Incorporated